



ABSTRACT OF THE DISCLOSURE

A wafer scale high density probe assembly having a substrate with a surface a plurality of bond wire elongated electrical conductors extending away from the substrate surface; wherein each of the bond wire elongated electrical conductors has a first end affixed to the substrate surface and a second end projecting away from the substrate surface; each of the first ends and second ends of the bond wire elongated electrical connectors having a ball-shaped protuberance positioned thereon; also wherein there is a sheet of material having a plurality of openings through which the second ends project, there being a perforation in the sheet in the vicinity of each of the openings permitting the second ends to move when the assembly is used to electrically probe an electronic device.